

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2017/12/20	Phebe Su
A1			Optimized molding	2018/08/10	Phebe Su

REMARK/注释:

1. CHARACTERISTICS/特性:

- 1.1、RATED VOLTAGE: 250V
额定电压: 250伏特
 - 1.2、RATED CURRENT: 3AMP
额定电流: 3安培
 - 1.3、CONTACT RESISTANCE: 25mohms MAX. INITIAL; 40mohms MAX. AFTER
接触阻抗: 初始 25mohms 最大; 最终 40mohms 最大
 - 1.4、INSULATION RESISTANCE: 1000Mohms MIN. at 500V DC
绝缘阻抗: 1000兆欧 最小, 在500伏直流电下
 - 1.5、DIELECTRIC STRENGTH: 500VRMS
耐电压: 500伏特
 - 1.6、OPERATING TEMPERATURE RANGE: -55℃~105℃
工作温度: -55℃~105℃
2. MATERIAL/材质:
- 2.1、INSULATORS: PBT+30% BULE
胶芯: PBT+30% 蓝色
 - 2.2、CONTACTS: BRASS C2800R-H, 80u"MIN BRIGHT TIN ,
40u"MIN NICKEL UNDER PLATE.
端子: 黄铜 (C2800R-H), 镍底40u"MIN, 镀亮锡80u"MIN.
 - 2.3、SHELL: SPCC, 50u"MIN NICKEL TOP OVER, 40u"MIN COPPER UNDER PLATE.
SALT MIST 12 hour.
外壳: SPCC, 铜底40u"MIN, 镀镍50u"MIN . 盐雾12小时。
 - 2.4、Z BRACKET: SPCC, 80u" BRIGHT TIN PLATED.
Z字片: 铁料, 镀亮锡80u"。
 - 2.5、SCREW: SPCC, 80-100U" NIKEL PLATED.
螺丝: SPCC. 镀镍80-100U"
3. MARKED Ⓢ SHOULD BE FAI, MARKED ▽ SHOULD BE QIP AND THE FIRST INSPECTION.
标记 Ⓢ 为FAI尺寸, 标记 ▽ 为重点管控尺寸及首件检验

MATRIX PART NO:

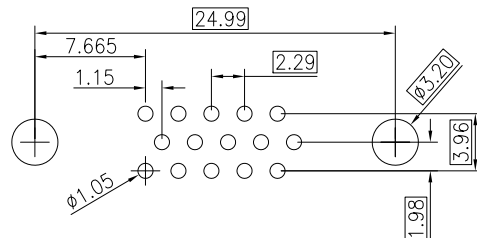
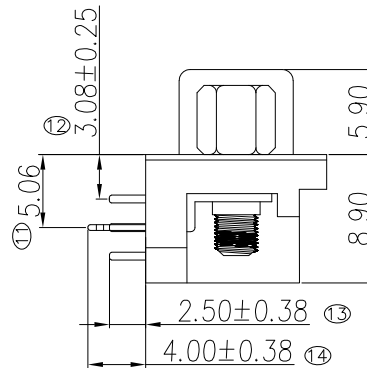
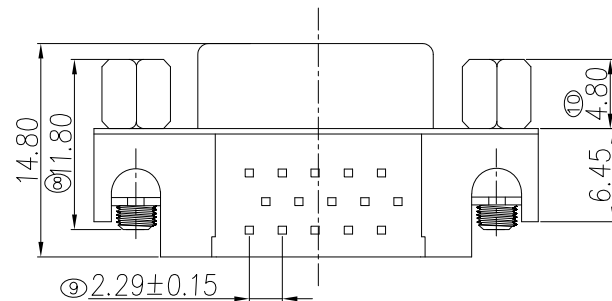
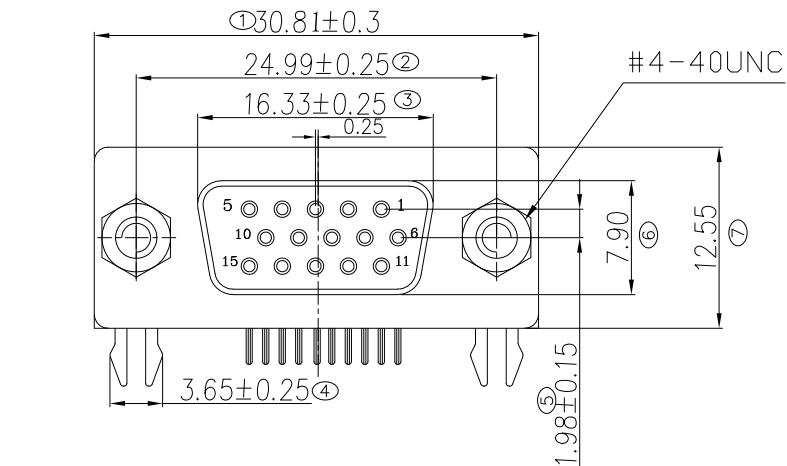
MATRIX D-SUB
Pin Number

MDS 15 - 01 - 33
Series number
Gold Plating
01: Gold Flash/Tin
10: 10u"
30: 30u"

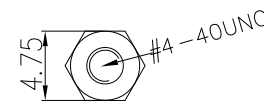
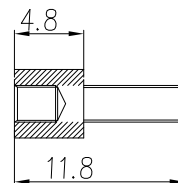


Matrix Electronics Co., Ltd

TOLERANCE: X:X X:XX X:XXX ANGLE: ±3°	DESIGN BY : Phebe Su	DATE : 2018/08/10	PART NAME: D-SUB Female 15P 叉锁(3.08) 不切边	
	CHECKED BY: Janice Liu	DATE : 2018/08/10	PART NO.	MDS15-01-33
	APPROVED BY1: Richard Hsieh	DATE : 2018/08/10	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2018/08/10	DRAW NO.	
SCALE: 1:1	SIZE: A4		SHEET NO.	1 OF 1



RECOMMENDED PCB LAYOUT THICKNESS=1.6mm
TOLERANCE: ±0.05



螺丝